

# FQD5P10

## P-Channel QFET® MOSFET

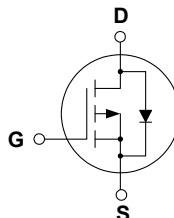
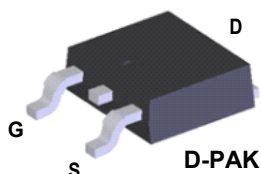
-100 V, -3.6 A, 1.05Ω

### Description

This P-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor®'s proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

### Features

- -3.6 A, -100 V,  $R_{DS(on)} = 1.05 \Omega$  (Max.) @  $V_{GS} = -10$  V,  $I_D = 1.8$  A
- Low Gate Charge (Typ. 6.3 nC)
- Low  $C_{rss}$  (Typ. 18 pF)
- 100% avalanche tested



### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FQD5P10	Unit
$V_{DSS}$	Drain-Source Voltage	-100	V
$I_D$	Drain Current - Continuous ( $T_C = 25^\circ\text{C}$ )	-3.6	A
	- Continuous ( $T_C = 100^\circ\text{C}$ )	-2.28	A
$I_{DM}$	Drain Current - Pulsed (Note 1)	-14.4	A
$V_{GSS}$	Gate-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	55	mJ
$I_{AR}$	Avalanche Current (Note 1)	-3.6	A
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	2.5	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	-6.0	V/ns
$P_D$	Power Dissipation ( $T_A = 25^\circ\text{C}$ ) *	2.5	W
	Power Dissipation ( $T_C = 25^\circ\text{C}$ )	25	W
	- Derate above $25^\circ\text{C}$	0.2	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	FQD5P10	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	5.0	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *	50	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	110	$^\circ\text{C}/\text{W}$

\* When mounted on the minimum pad size recommended (PCB Mount)

## Electrical Characteristics

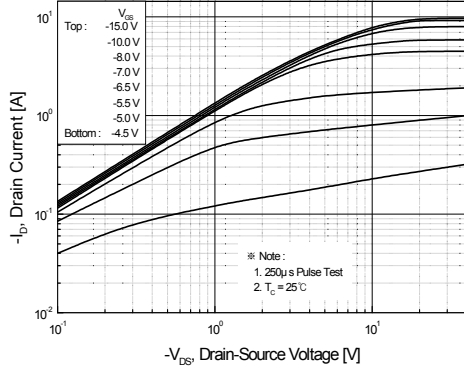
$T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = -250\ \mu\text{A}$	-100	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = -250\ \mu\text{A}$ , Referenced to $25^\circ\text{C}$	--	-0.1	--	V/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = -100\text{ V}, V_{GS} = 0\text{ V}$	--	--	-1	$\mu\text{A}$
		$V_{DS} = -80\text{ V}, T_C = 125^\circ\text{C}$	--	--	-10	$\mu\text{A}$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\ \mu\text{A}$	-2.0	--	-4.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = -10\text{ V}, I_D = -1.8\text{ A}$	--	0.82	1.05	$\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = -40\text{ V}, I_D = -1.8\text{ A}$	--	2.3	--	S
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = -25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	190	250	pF
$C_{oss}$	Output Capacitance		--	70	90	pF
$C_{rss}$	Reverse Transfer Capacitance		--	18	25	pF
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = -50\text{ V}, I_D = -4.5\text{ A},$ $R_G = 25\ \Omega$	--	9	30	ns
$t_r$	Turn-On Rise Time		--	70	150	ns
$t_{d(off)}$	Turn-Off Delay Time		--	12	35	ns
$t_f$	Turn-Off Fall Time		(Note 4)	--	30	70
$Q_g$	Total Gate Charge	$V_{DS} = -80\text{ V}, I_D = -4.5\text{ A},$ $V_{GS} = -10\text{ V}$	--	6.3	8.2	nC
$Q_{gs}$	Gate-Source Charge		--	1.7	--	nC
$Q_{gd}$	Gate-Drain Charge		(Note 4)	--	3.0	--
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain-Source Diode Forward Current		--	--	-3.6	A
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current		--	--	-14.4	A
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = -3.6\text{ A}$	--	--	-4.0	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_S = -4.5\text{ A},$ $di_F / dt = 100\text{ A}/\mu\text{s}$	--	85	--	ns
$Q_{rr}$	Reverse Recovery Charge		--	0.27	--	$\mu\text{C}$

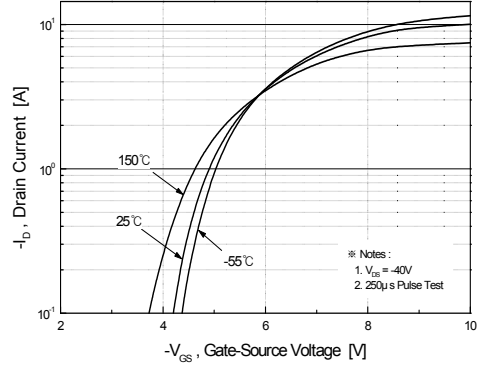
**Notes:**

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2.  $L = 6.4\text{ mH}, I_{AS} = -3.6\text{ A}, V_{DD} = -25\text{ V}, R_G = 25\ \Omega$ , Starting  $T_J = 25^\circ\text{C}$
3.  $I_{SD} \leq -4.5\text{ A}, di/dt \leq 300\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ\text{C}$
4. Essentially independent of operating temperature

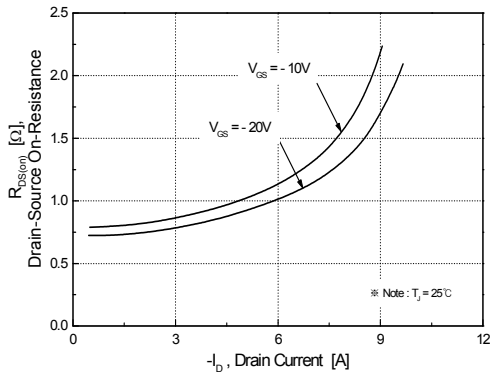
### Typical Characteristics



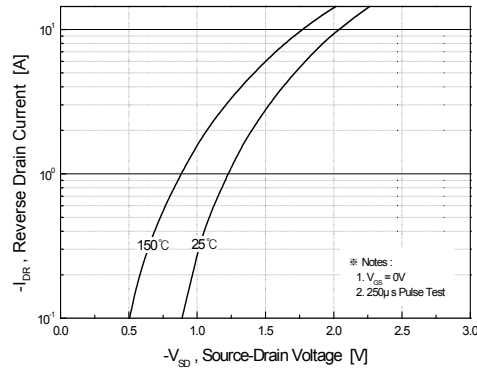
**Figure 1. On-Region Characteristics**



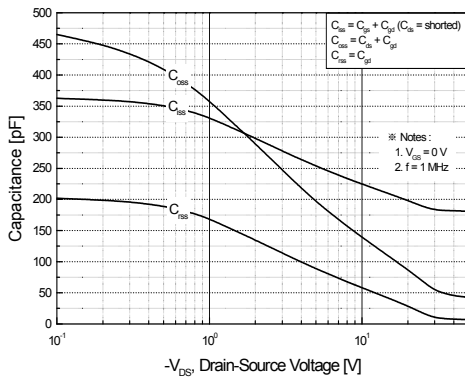
**Figure 2. Transfer Characteristics**



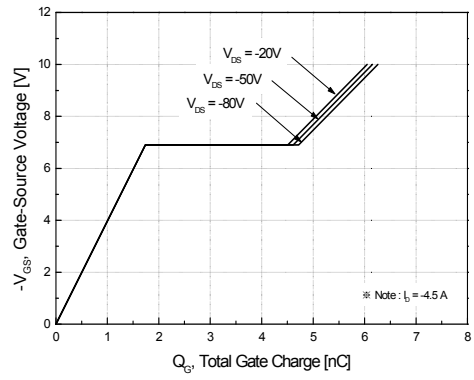
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**

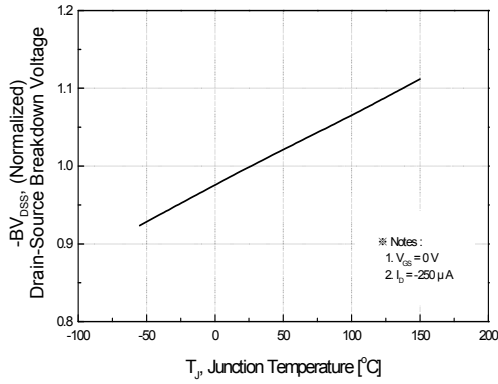


**Figure 5. Capacitance Characteristics**

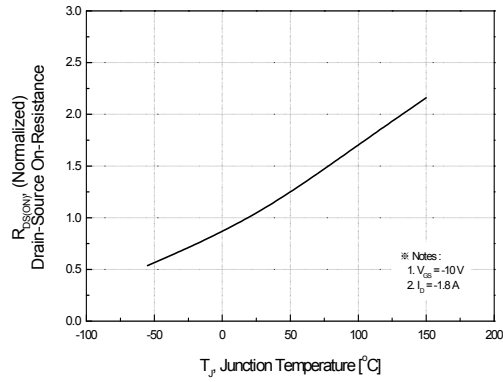


**Figure 6. Gate Charge Characteristics**

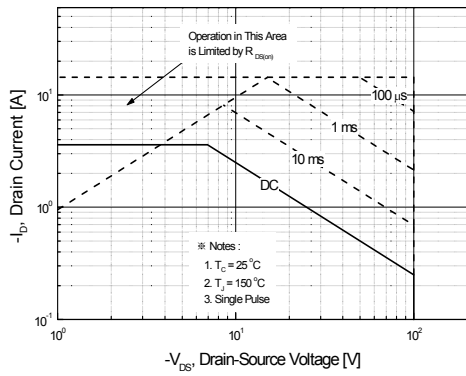
**Typical Characteristics** (Continued)



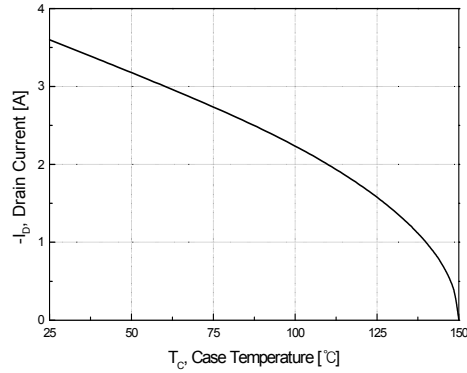
**Figure 7. Breakdown Voltage Variation vs. Temperature**



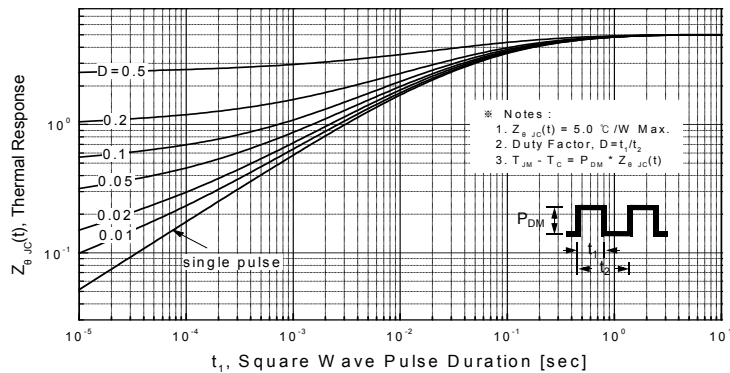
**Figure 8. On-Resistance Variation vs. Temperature**



**Figure 9. Maximum Safe Operating Area**

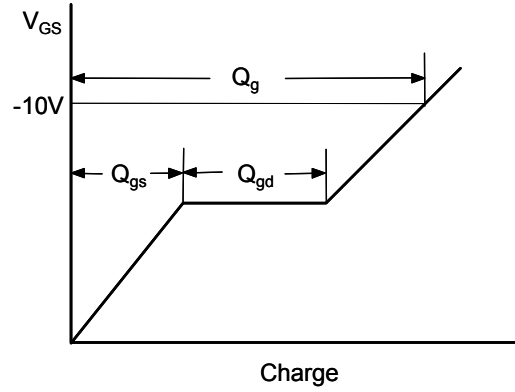
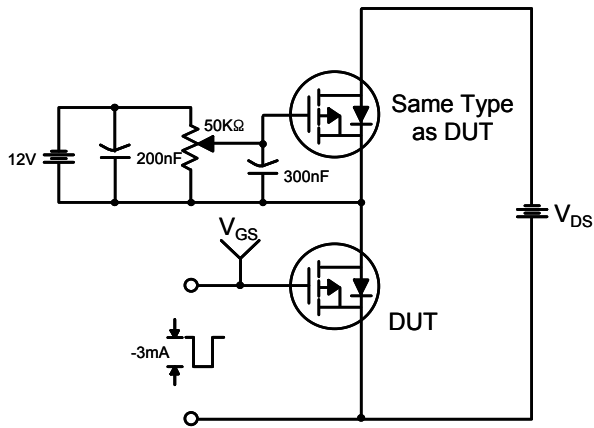


**Figure 10. Maximum Drain Current vs. Case Temperature**

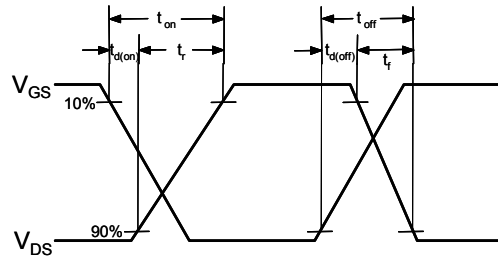
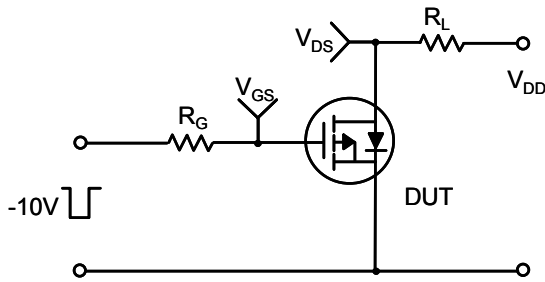


**Figure 11. Transient Thermal Response Curve**

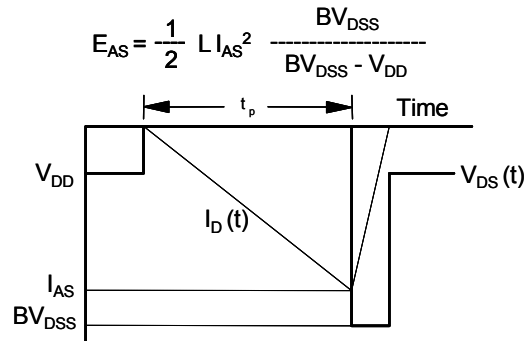
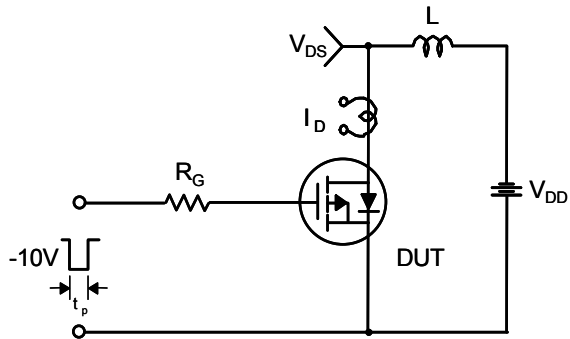
**Gate Charge Test Circuit & Waveform**



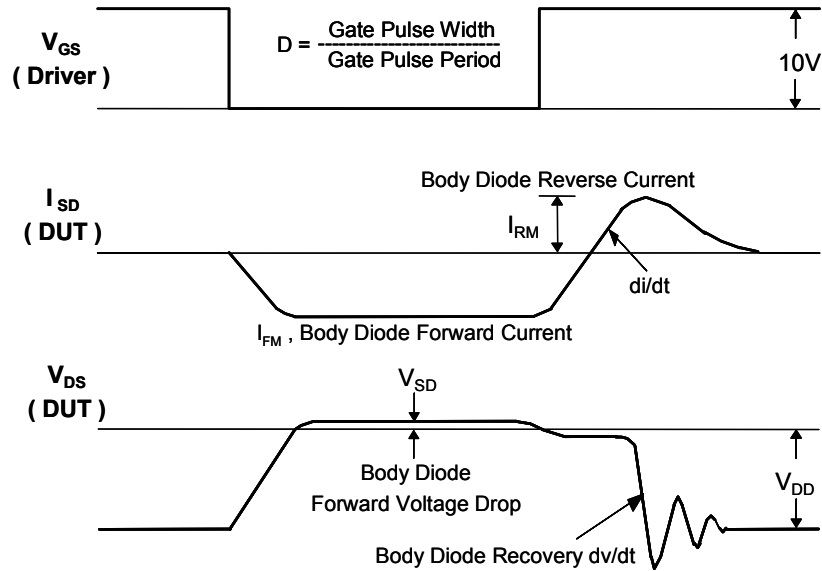
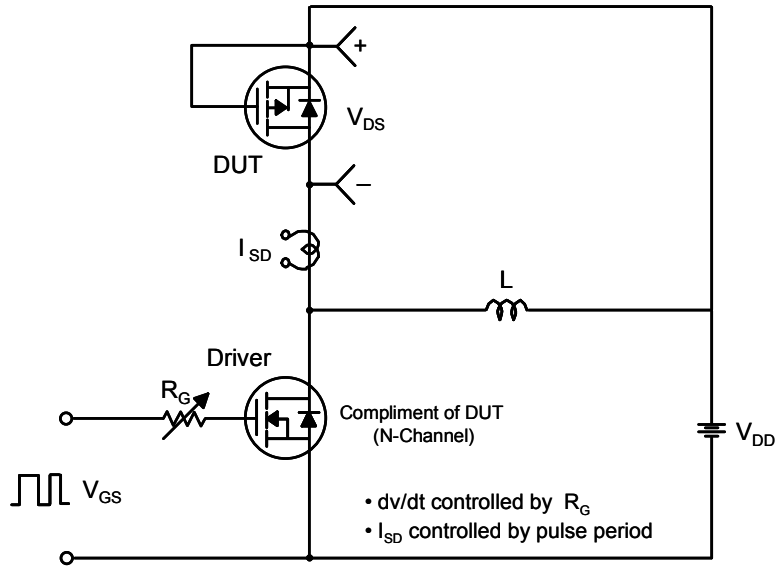
**Resistive Switching Test Circuit & Waveforms**



**Unclamped Inductive Switching Test Circuit & Waveforms**

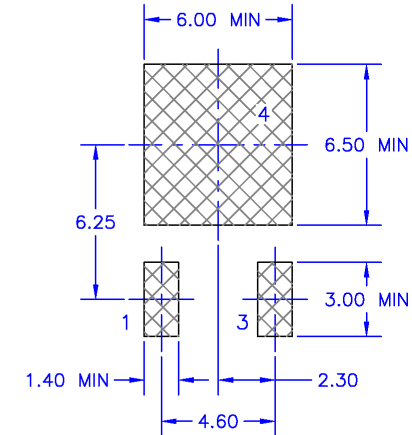
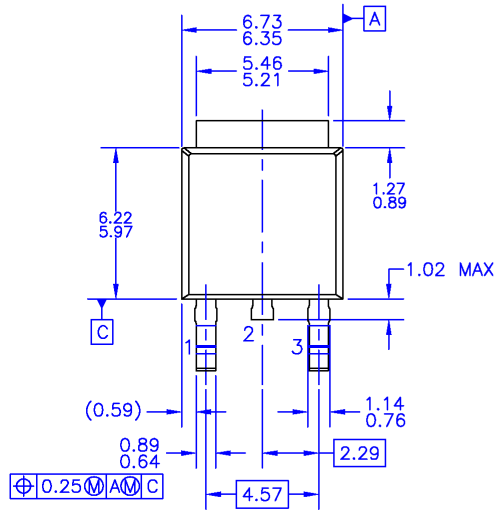


Peak Diode Recovery dv/dt Test Circuit & Waveforms

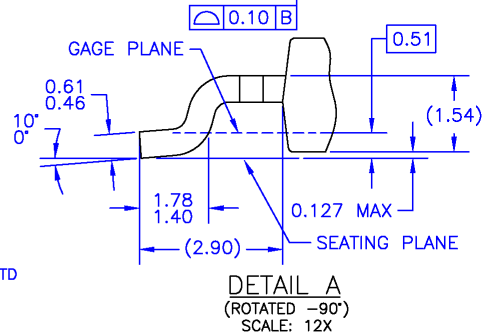
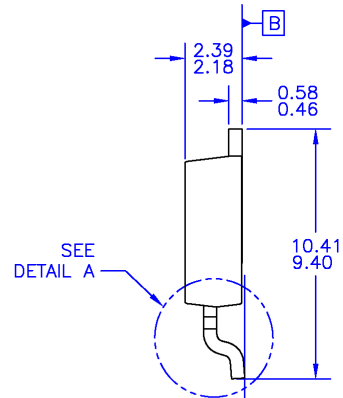
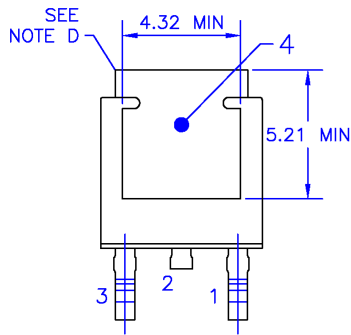


## Package Dimensions

### D-PAK



LAND PATTERN RECOMMENDATION



DETAIL A  
(ROTATED -90°)  
SCALE: 12X


- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE CONFORMS TO JEDEC, TO-252, ISSUE C, VARIATION AA.
  - B) ALL DIMENSIONS ARE IN MILLIMETERS.
  - C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
  - D) HEAT SINK TOP EDGE COULD BE IN CHAMFERED CORNERS OR EDGE PROTRUSION.
  - E) PRESENCE OF TRIMMED CENTER LEAD IS OPTIONAL.
  - F) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
  - G) LAND PATTERN RECOMMENDATION IS BASED ON IPC7351A STD TO220P1003X238-3N.
  - H) DRAWING NUMBER AND REVISION: MKT-T0252A03REV8

Dimensions in Millimeters



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| AccuPower™  | F-PFST™   | PowerXS™                              | SYSTEM GENERAL®* |
| AX-CAP®*  | FRFET®  | Programmable Active Droop™            | TinyBoost™       |
| BitSiC™   | Global Power Resource <sup>SM</sup>             | QFET®                                 | TinyBuck™        |
| Build it Now™   | Green Bridge™                                   | QS™                                   | TinyCalc™        |
| CorePLUS™   | Green FPS™                                      | Quiet Series™                         | TinyLogic®       |
| CorePOWER™  | Green FPS™ e-Series™                            | RapidConfigure™                       | TINYOPTO™        |
| CROSSVOLT™  | Gmax™   | ™                                     | TinyPower™       |
| CTL™  | GTO™  | Saving our world, 1mW/W/kW at a time™ | TinyPWM™         |
| Current Transfer Logic™   | IntelliMAX™                                     | SignalWise™                           | TinyWire™        |
| DEUXPEED®   | ISOPANAR™                                       | SmartMax™                             | TranSiC®         |
| Dual Cool™  | Marking Small Speakers Sound Louder and Better™ | SMART START™                          | TriFault Detect™ |
| EcoSPARK®   | MegaBuck™                                       | Solutions for Your Success™           | TRUECURRENT®*    |
| EfficientMax™   | MICROCOUPLER™                                   | SPM®                                  | µSerDes™         |
| ESBC™   | MicroFET™                                       | STEALTH™                              | µSerDes™         |
|  | MicroPak™                                       | SuperFET®                             | UHC®             |
| Fairchild®  | MicroPak2™                                      | SuperSOT™-3                           | Ultra FRFET™     |
| Fairchild Semiconductor®  | MillerDrive™                                    | SuperSOT™-6                           | UniFET™          |
| FACT Quiet Series™  | MotionMax™                                      | SuperSOT™-8                           | VCX™             |
| FACT®   | mWSaver™  | SupreMOS®                             | VisualMax™       |
| FAST®   | OptoHit™  | SynCFET™                              | VoltagePlus™     |
| FastvCore™  | OPTOLOGIC®                                      |                                       | XS™              |
| FETBench™   | OPTOPLANAR®                                     |                                       |                  |

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- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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**PRODUCT STATUS DEFINITIONS**

**Definition of Terms**

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.